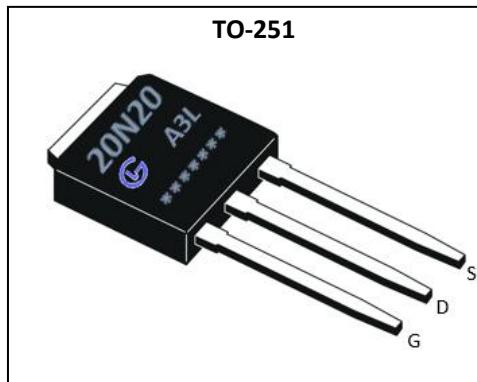


General Description:

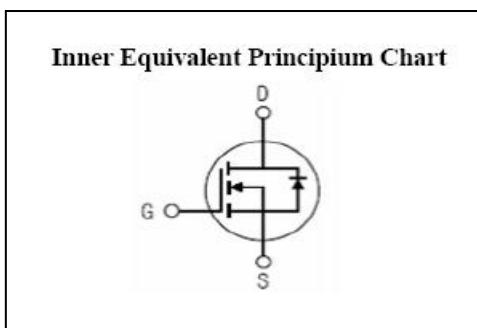
GL20N20A3L the silicon N-channel Enhanced VDMOSFETS, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency. The package form is TO-251, which accords with the RoHS standard.

V _{DSS}	200	V
I _D	20	A
P _D (T _C =25 °C)	96	W
R _{DS(ON)max}	0.12	Ω



Features:

- Fast Switching
- Low Gate Charge and Rdson
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test



Applications:

- LED Lighting
- Charger
- Standby Power

Absolute (T_C= 25 °C unless otherwise specified):

Symbol	Parameter	Rating	Units
V _{DSS}	Drain-to-Source Voltage	200	V
I _D	Continuous Drain Current	20	A
	Continuous Drain Current T _C = 100 °C	12.7	A
I _{DM} ^{a1}	Pulsed Drain Current	80	A
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS} ^{a2}	Single Pulse Avalanche Energy	500	mJ
dv/dt ^{a3}	Peak Diode Recovery dv/dt	5.0	V/ns
P _D	Power Dissipation	96	W
	Derating Factor above 25°C	0.77	W/°C
T _J , T _{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	°C
T _L	Maximum Temperature for Soldering	300	°C



GL20N20A3L

GL Silicon N-Channel Power MOSFET

Electrical Characteristics ($T_c = 25^\circ C$ unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	200	--	--	V
$\Delta V_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	$I_D=250\mu A$, Reference $25^\circ C$	--	0.21	--	$V/^\circ C$
I_{DSS}	Drain to Source Leakage Current	$V_{DS}=200V, V_{GS}=0V, T_a=25^\circ C$	--	--	1	μA
		$V_{DS}=160V, V_{GS}=0V, T_a=125^\circ C$	--	--	100	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=+20V$	--	--	100	μA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=-20V$	--	--	-100	μA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10V, I_D=10A$	--	--	0.12	Ω
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=5V, I_D=8A$	--	--	0.125	Ω
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=3V, I_D=6A$	--	--	0.135	Ω
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	--	1.5	V
Pulse width $t_p \leq 300\mu s, \delta \leq 2\%$						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=10A$	--	50	--	S
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=25V$	--	1600	--	pF
C_{oss}	Output Capacitance	$f=1.0MHz$	--	190	--	
C_{rss}	Reverse Transfer Capacitance		--	60	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D=20A, V_{DD}=100V$ $R_G=10\Omega$	--	24	--	ns
t_r	Rise Time		--	42	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	45	--	
t_f	Fall Time		--	15	--	
Q_g	Total Gate Charge	$I_D=20A, V_{DD}=100V$ $V_{GS}=5V$	--	26	--	nC
Q_{gs}	Gate to Source Charge		--	9	--	
Q_{gd}	Gate to Drain ("Miller")Charge		--	9.5	--	



GL20N20A3L

GL Silicon N-Channel Power MOSFET

Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I _S	Continuous Source Current (Body Diode)		--	--	20	A
I _{SM}	Maximum Pulsed Current (Body Diode)		--	--	80	A
V _{SD}	Diode Forward Voltage	I _S =20A, V _{GS} =0V	--	--	1.5	V
trr	Reverse Recovery Time	I _S =20A, T _j =25°C dI _F /dt=100A/us, V _{GS} =0V	--	245	--	ns
Qrr	Reverse Recovery Charge		--	1200	--	uC
IRRM	Reverse Recovery Current		--	12.8	--	A

Pulse width tp≤300μs, δ≤2%

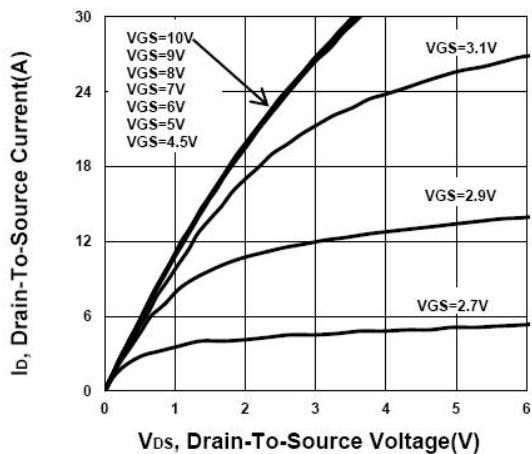
Symbol	Parameter	Typ.	Units
R _{θJC}	Junction-to-Case	1.30	°C/W
R _{θJA}	Junction-to-Ambient	83.3	°C/W

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

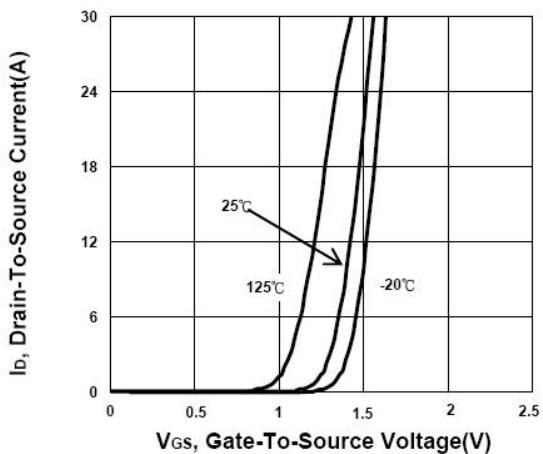
^{a2}: L=10.0mH, I_D=13A, Start T_j=25°C

^{a3}: I_{SD} =209A, di/dt ≤100A/us, V_{DD}≤BV_{DS}, Start T_j=25°C

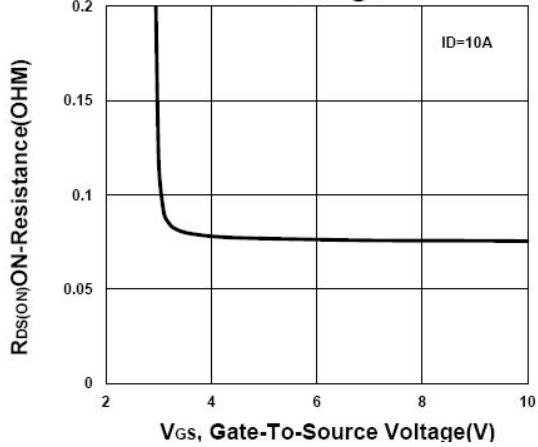
Output Characteristics



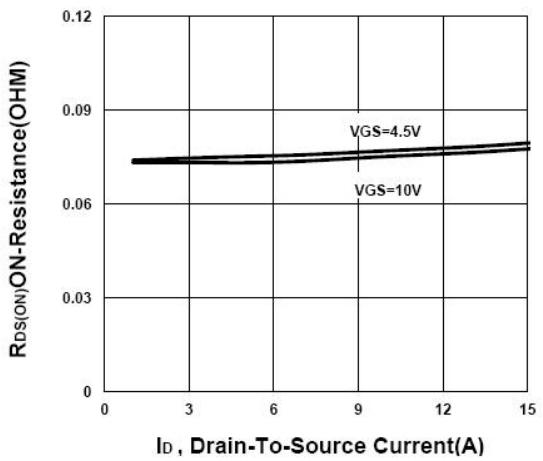
Transfer Characteristics



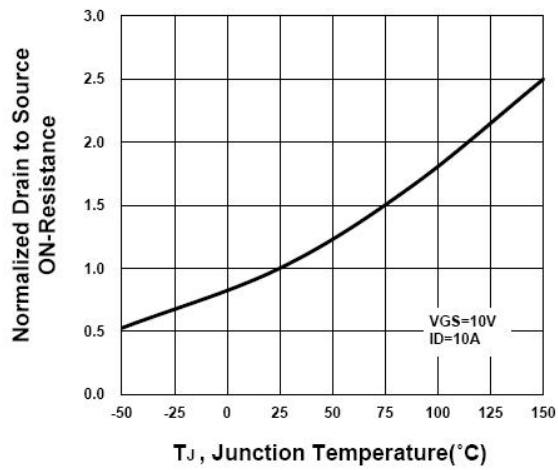
On-Resistance VS Gate-To-Source Voltage



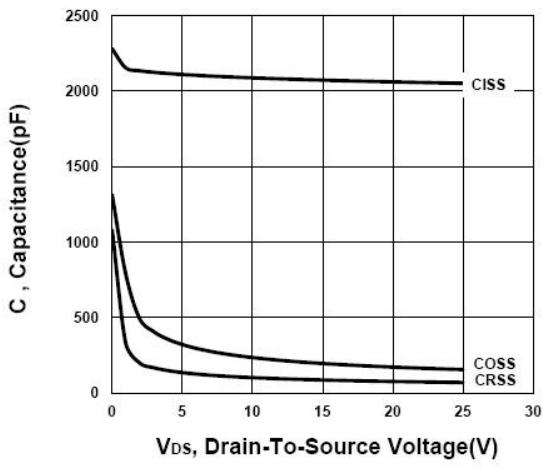
On-Resistance VS Drain Current

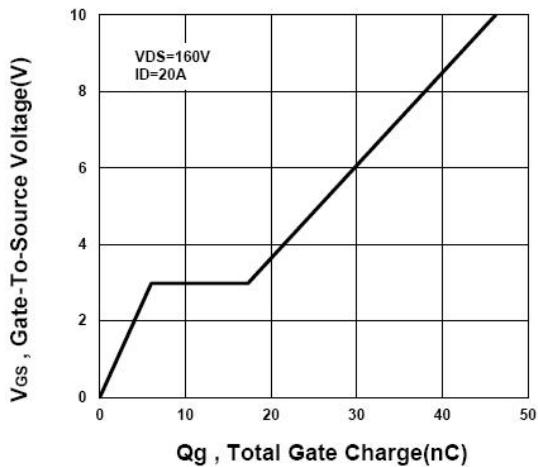
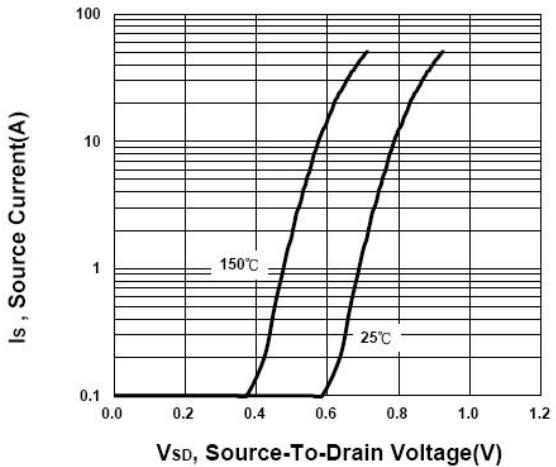
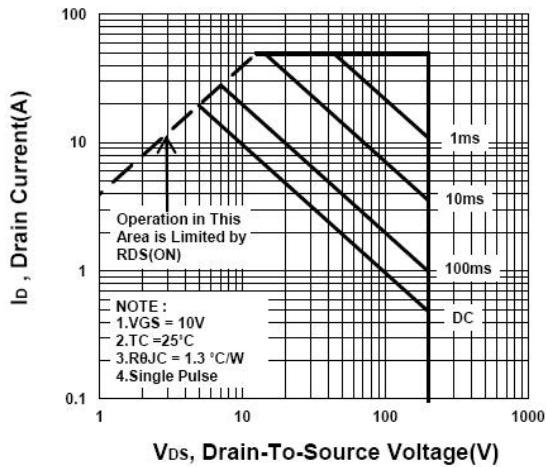
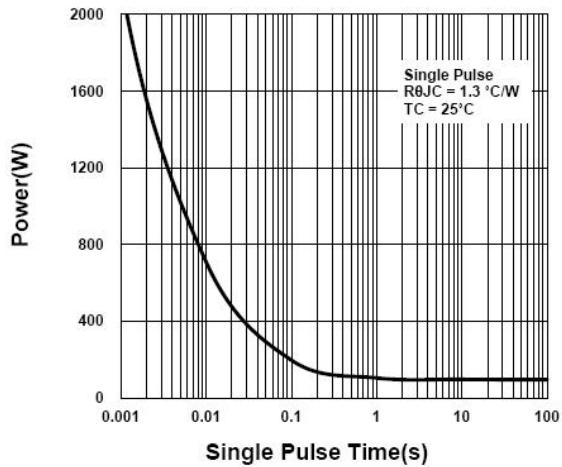


On-Resistance VS Temperature



Capacitance Characteristic



Gate charge Characteristics

Source-Drain Diode Forward Voltage

Safe Operating Area

Single Pulse Maximum Power Dissipation

Transient Thermal Response Curve
